



## Material Content Data Sheet



<b>Sales Product Name</b>		BAS 40-02L E6327		<b>Issued</b>		4. March 2019		
<b>MA#</b>		MA005097546						
<b>Package</b>		PG-TSLP-2-1		<b>Weight*</b>		0.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.11		1063	
	noble metal	gold	7440-57-5	0.002	0.41		4125	
	inorganic material	silicon	7440-21-3	0.026	5.04	5.56	50360	55548
leadframe	non noble metal	nickel	7440-02-0	0.100	19.74	19.74	197388	197388
wire	noble metal	gold	7440-57-5	0.006	1.12	1.12	11177	11177
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		358	
	organic material	carbon black	1333-86-4	0.004	0.72		7168	
	plastics	epoxy resin	-	0.049	9.68		96754	
	inorganic material	silicondioxide	60676-86-0	0.311	61.22	71.66	612423	716703
leadfinish	noble metal	gold	7440-57-5	0.010	1.90	1.90	18993	18993
plating	noble metal	palladium	7440-05-3	0.000	0.01		73	
	noble metal	gold	7440-57-5	0.000	0.01	0.02	118	191
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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